

6/28/03

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS
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Application Number: 10/604,164

Confirmation Number:

First Named Applicant: Leonard J Gardecki

Attorney Docket Number: BUR920030026US1

Art Unit: 2823

Examiner: B. K. Ebede

Search string: (6354917 or 6354917 or 6354917 or 6354917 or 6354917 or 6354917 or 6354917).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
B11	1	6354917	2002-03- 12	Ball	B1	451	41
B11	2	6342434	2002-01- 29	Miyamoto et al	B1	438	464
B11	3	6133136	2000-10- 17	Edelstein et al		438	618
B11	4	6219910	2001-04- 24	Murali	B1	29	840
B11	5	4434434	1984-02- 28	Bhattacharya et al		357	71
B11	6	3458925	1969-08- 05	Napier et al		29	578

Remarks

Note: Remarks are not for responding to an office action.

Signature

Examiner Name	Date
B. K. Ebede	11/8/2003